

MA3DJ92

Silicon epitaxial planar type

For rectification
Common cathode type

■ Features

- Forward current (Average) $I_{F(AV)} = 20$ A rectification is possible
- High reverse voltage V_R

■ Packaging

Tray: 50 pcs

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	100	V
Forward current (Average) *1	Single	10	A
	Double	20	
Non-repetitive peak forward surge current *2	I_{FSM}	80	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +125	$^\circ\text{C}$

Note) *1: $T_C = 90^\circ\text{C}$

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10$ A, Per diode		0.80	0.86	V
Reverse current	I_R	$V_R = 100$ V, Per diode		0.6	100	μA
Thermal resistance (j-c)	$R_{th(j-c)}$				3	$^\circ\text{C/W}$
Thermal resistance (j-a)	$R_{th(j-a)}$				63	$^\circ\text{C/W}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

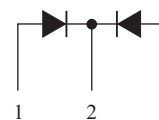
2. Absolute frequency of input and output is 10 MHz

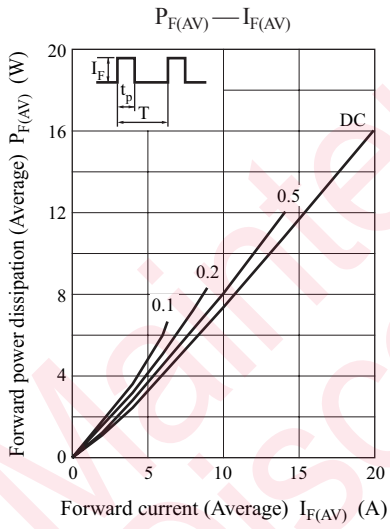
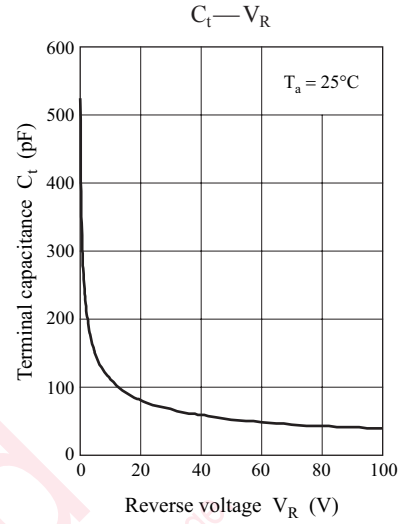
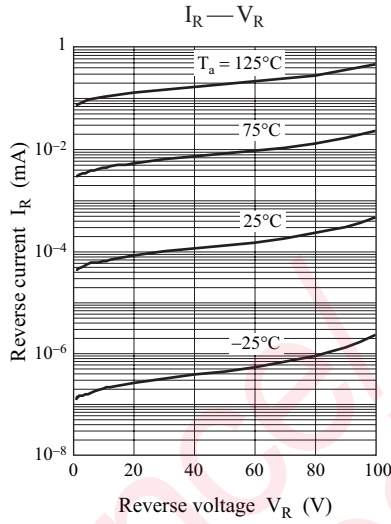
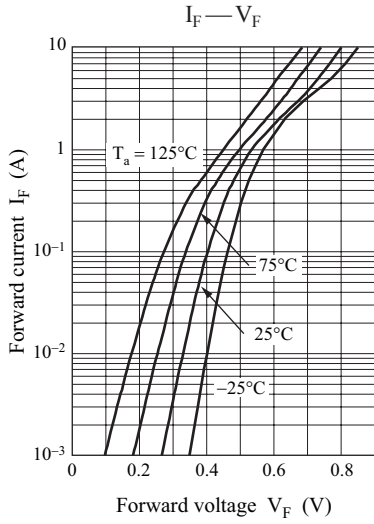
■ Package

- Code
TO-220D-A1
- Pin Name
1: Anode
2: Cathode
3: Anode

■ Marking Symbol: MA3DJ92

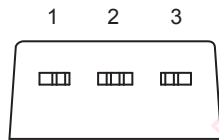
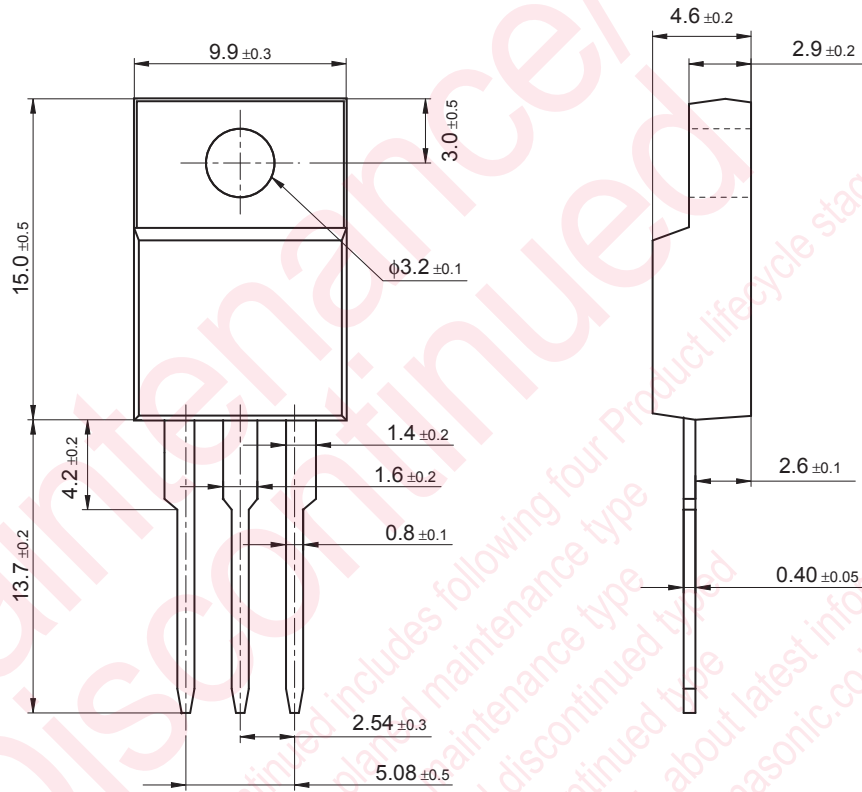
■ Internal Connection





TO-220D-A1

Unit: mm



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